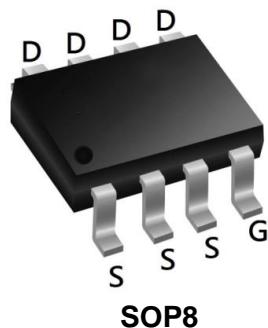
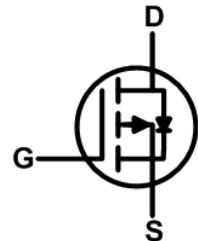


Product Summary

BVDSS	RDS(on)	ID
-30V	8mΩ	-18A



- 100% EAS Guaranteed
- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology



Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source voltage	V_{DS}	-30	V
Gate-Source voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	-18	A
		-8.8	
Pulsed Drain Current ¹	I_{DM}	-53	A
Single Pulse Avalanche Energy ²	EAS	80	mJ
Total Power Dissipation	P_D	3	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

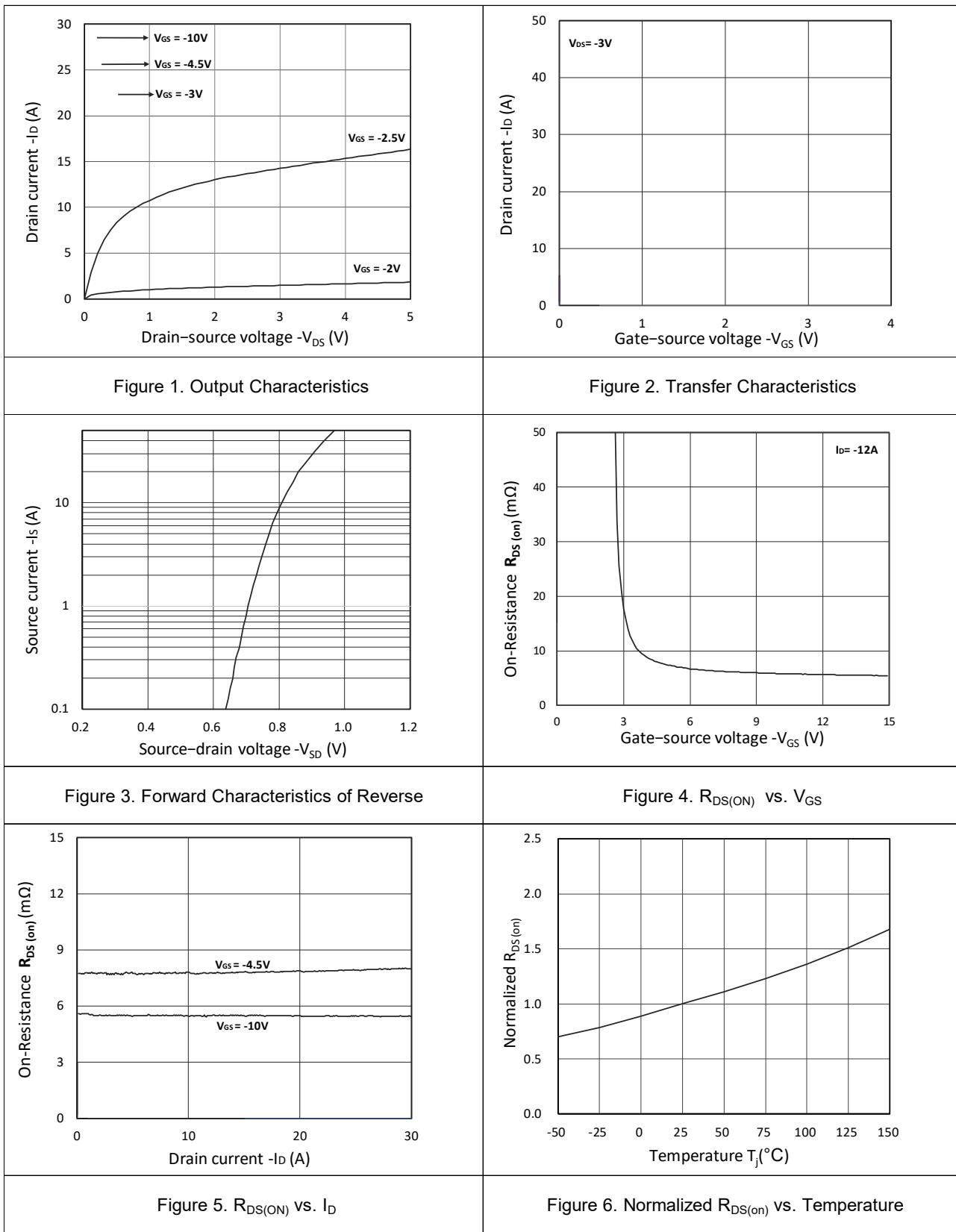
Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	41.6	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = -30\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	-1	μA
$T_J=100^\circ\text{C}$			-	-	-100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-	-2.5	V
Drain-Source On-Resistance ⁴	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -12\text{A}$	-	8	10.4	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -10\text{A}$	-	11	14	
Forward Transconductance ⁴	g_{fs}	$V_{\text{DS}} = -10\text{V}, I_D = -10\text{A}$	-	50	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	3100	-	pF
Output Capacitance	C_{oss}		-	430	-	
Reverse Transfer Capacitance	C_{rss}		-	358	-	
Gate Resistance	R_g	$f = 1\text{MHz}$	-	9.5	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{\text{GS}} = -10\text{V}, V_{\text{DS}} = -15\text{V}, I_D = -12\text{A}$	-	35	-	nC
Gate-Source Charge	Q_{gs}		-	9.9	-	
Gate-Drain Charge	Q_{gd}		-	10.5	-	
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, V_{\text{DD}} = -15\text{V}, R_G = 3\Omega, I_D = -12\text{A}$	-	10.8	-	ns
Rise Time	t_r		-	13.2	-	
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	73	-	
Fall Time	t_f		-	35	-	
Reverse Recovery Time	t_{rr}	$I_F = -12\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	-	25	-	ns
Reverse Recovery Charge	Q_{rr}		-	10	-	nC
Drain-source body diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = -1\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	$T_A=25^\circ\text{C}$	I_S	-	-	-14	A

Typical Characteristics



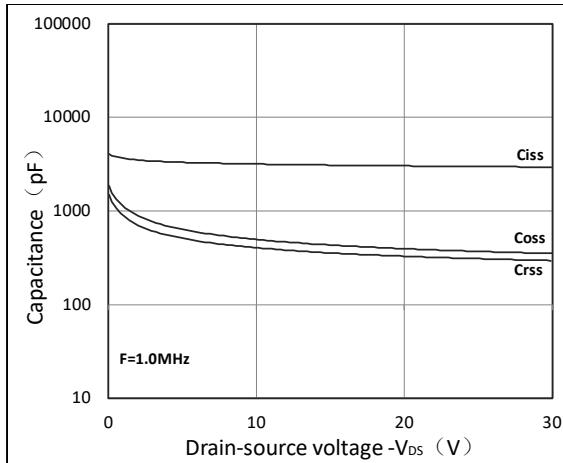


Figure 7. Capacitance Characteristics

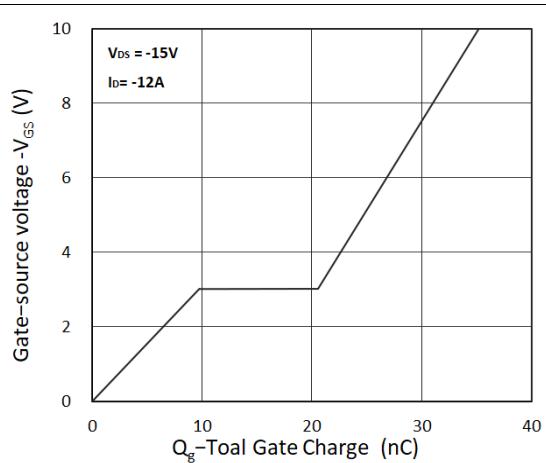


Figure 8. Gate Charge Characteristics

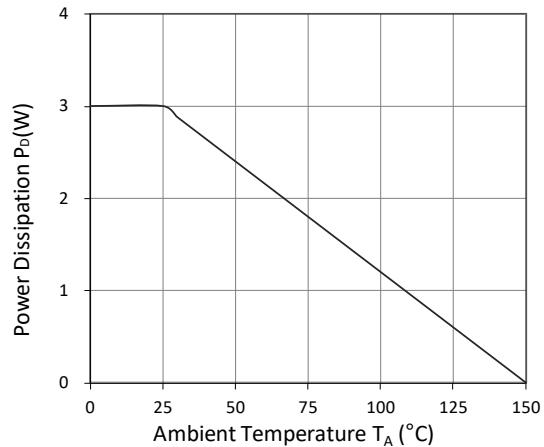


Figure 9. Power Dissipation

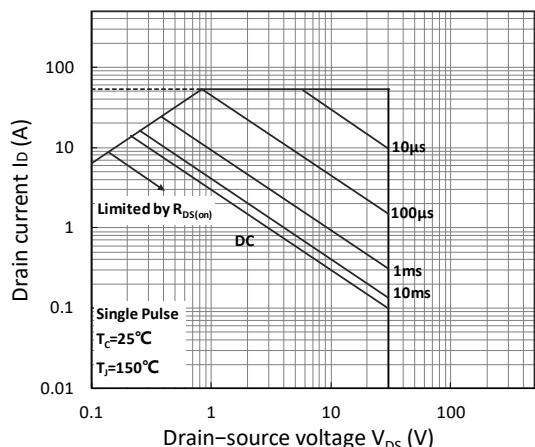


Figure 10. Safe Operating Area

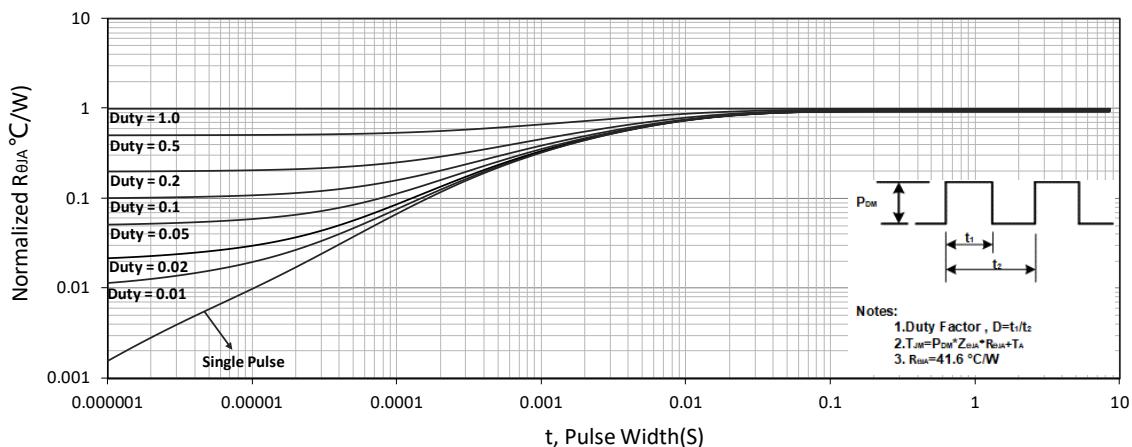
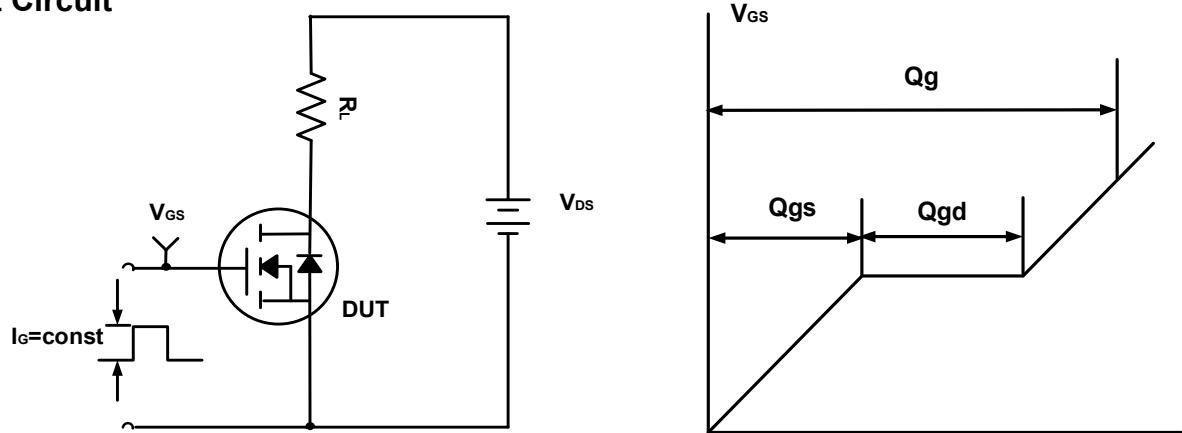
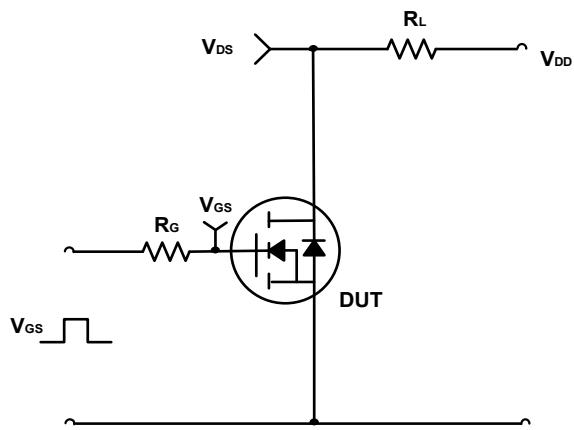
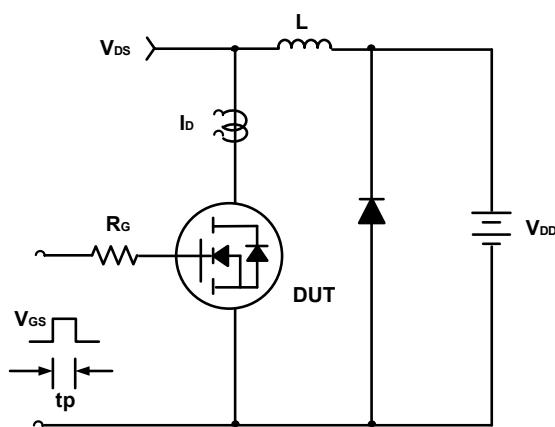
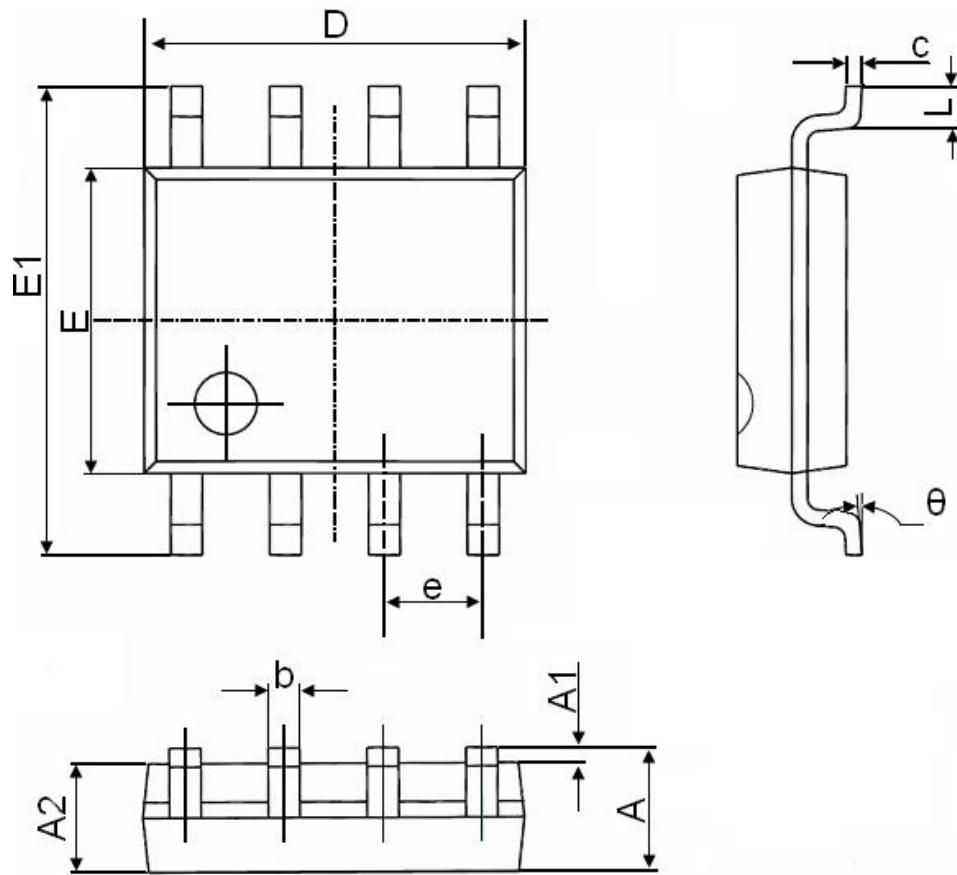


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

Figure A. Gate Charge Test Circuit & Waveforms

Figure B. Switching Test Circuit & Waveforms

Figure C. Unclamped Inductive Switching Circuit & Waveforms

SOP-8 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°